WHAT IS CLAIMED IS:

1. A method for forming a silicon-containing insulation film on a substrate by plasma polymerization, comprising the steps of:

introducing a reaction gas comprising (i) a source gas comprising a siliconcontaining hydrocarbon compound containing at least one vinyl group (Si-vinyl compound), and (ii) an additive gas, into a reaction chamber where a substrate is placed; and

applying radio-frequency power to the gas to cause plasma polymerization, thereby depositing an insulation film on the substrate.

- 2. The method according to Claim 1, wherein the Si-vinyl compound is a compound or compounds selected from the group consisting of linear silicon-containing hydrocarbon compounds having the formula $Si_{\alpha}O_{\alpha-1}R_{2\alpha-\beta+2}(OR)_{\beta}$ wherein α is an integer of 1-3, β is 0, 1, or 2, R is C_{1-6} saturated or unsaturated hydrocarbon, and at least one R attached to Si contains a vinyl group; cyclic compounds having the formula $Si_nO_nR_{2n}$, wherein n is an integer of 3-6, R is C_{1-6} saturated or unsaturated hydrocarbon, and at least one R attached to Si contains a vinyl group; and cyclic compounds having the formula $Si_p(C_2H_2)_pR_{2p}$ wherein p is an integer of 3-6, and R is C_{1-6} saturated or unsaturated hydrocarbon.
- 3. The method according to Claim 2, wherein R is $-C_zH_{2(z-w)+1}$ wherein z is an integer of 2-4, and w represents the number of unsaturated carbon bonds and is an integer of 1-3.
- 4. The method according to Claim 3, wherein the Si-vinyl compound is a liner compound wherein α is 1 and β is 0.
 - 5. The method according to Claim 4, wherein the compound is $(CH_3)_2Si(C_2H_3)_2$.
- 6. The method according to Claim 2, wherein the Si-vinyl compound is a cyclic compound wherein n is 3.
- 7. The method according to Claim 1, wherein the source gas further comprises a silicon-containing hydrocarbon compound (Si compound) having no vinyl group.
- 8. The method according to Claim 7, wherein the Si compound is a compound or compounds selected from the group consisting of linear compounds having the formula $Si_{\alpha}O_{\alpha-1}R_{2\alpha-\beta+2}(OR)_{\beta}$ wherein α is an integer of 1-3, β is 0, 1, or 2, R is C_{1-6} saturated

hydrocarbon; and cyclic compounds having the formula $Si_nO_nR_{2n}$, wherein n is an integer of 3-6, R is C_{1-6} saturated hydrocarbon.

- 9. The method according to Claim 7, wherein the flow ratio of the Si-vinyl compound to the Si compound is in the range of 10% to 100%.
- 10. The method according to Claim 1, wherein the additive gas is selected from the group consisting of a carrier gas, an oxidizing gas, and a plasma stabilizing gas.
- 11. The method according to Claim 10, wherein the plasma stabilizing gas is selected from the group consisting of H_2 , C_nH_{2n+2} , C_nH_{2n} , and $C_nH_{2n+1}OH$ wherein n is an integer of 1-5.
- 12. The method according to Claim 10, wherein the oxidizing gas is selected from the group consisting of O₂, CO₂, H₂O, O₃, and NO₂.
- 13. The method according to Claim 10, wherein the carrier gas is an inert gas selected from the group consisting of He, Ar, and N₂.
- 14. The method according to Claim 1, wherein the radio-frequency power is high-frequency power.
- 15. The method according to Claim 14, wherein the high-frequency power has a frequency of 2MHz or higher.
- 16. The method according to Claim 7, wherein the ratio is controlled to obtain a siloxan polymer having a film stress of 40 MPa or lower and a dielectric constant of 3.0 or lower.
- 17. The method according to Claim 1, wherein the Si-vinyl compound does not contain Si-O bonds, and the insulation film is a hard film composed of a silicon carbide material.
- 18. A method for forming a silicon-containing insulation film on a substrate by plasma polymerization, comprising the steps of:

introducing a reaction gas comprising (i) a source gas comprising a siliconcontaining hydrocarbon compound containing at least one vinyl group (Si-vinyl compound); (ii) a silicon-containing hydrocarbon compound (Si compound) having no vinyl group; and (iii) an additive gas, into a reaction chamber where a substrate is placed; controlling the ratio of the Si-vinyl compound to the Si compound in the range of 50% to 100%; and

applying radio-frequency power to the gas to cause plasma polymerization, thereby depositing an insulation film on the substrate.

- The method according to Claim 18, wherein the Si-vinyl compound is a compound or compounds selected from the group consisting of linear silicon-containing hydrocarbon compounds having the formula $Si_{\alpha}O_{\alpha-1}R_{2\alpha-\beta+2}(OR)_{\beta}$ wherein α is an integer of 1-3, β is 0, 1, or 2, R is C_{1-6} saturated or unsaturated hydrocarbon, and at least one R attached to Si contains a vinyl group; cyclic compounds having the formula $Si_{n}O_{n}R_{2n}$, wherein n is an integer of 3-6, R is C_{1-6} saturated or unsaturated hydrocarbon, and at least one R attached to Si contains a vinyl group; and linear compounds having the formula R-(SiR₃)_p-H wherein p is an integer of 1-3, and R is C_{1-6} saturated or unsaturated hydrocarbon, and at least one R attached to Si contains a vinyl group.
- 20. The method according to Claim 18, wherein the Si compound is a compound or compounds selected from the group consisting of linear compounds having the formula $Si_{\alpha}O_{\alpha-1}R_{2\alpha-\beta+2}(OR)_{\beta}$ wherein α is an integer of 1-3, β is 0, 1, or 2, R is C_{1-6} saturated hydrocarbon; and cyclic compounds having the formula $Si_{n}O_{n}R_{2n}$, wherein n is an integer of 3-6, R is C_{1-6} saturated hydrocarbon.
- 21. The method according to Claim 18, wherein the additive gas is selected from the group consisting of a carrier gas, an oxidizing gas, and a plasma stabilizing gas.
- 22. The method according to Claim 18, wherein the radio-frequency power is high-frequency power.
- 23. The method according to Claim 18, wherein the ratio is controlled to obtain a siloxan polymer having a film stress of 40 MPa or lower and a dielectric constant of 3.0 or lower.
- 24. The method according to Claim 17, wherein the Si-vinyl compound and the Si compound do not contain Si-O bonds, and the insulation film is a hard film composed of a silicon carbide material.